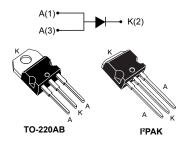


STPS20SM100S

Datasheet

100 V power Schottky rectifier



Features

- High current capability
- Avalanche rated
- Low forward voltage drop
- High frequency operation
- ECOPACK[®]2 compliant

Applications

- Switching diode
- SMPS
- DC/DC converter
- LED lighting
- Desktop power supply

Description

This single Schottky rectifier is suited for high frequency switch mode power supply.

Packaged in TO-220AB and I²PAK, the STPS20SM100S is intended to be used in notebook, game station and desktop adaptors, providing in these applications a good efficiency at both low and high load.

Product status link				
STPS20SM100S				
Product summary				
I _{F(AV)}	І_{F(AV)} 20 А			
V _{RRM}	100 V			
T _j (max.) 150 °C				
V _F (typ.)	0.63 V			

1 Characteristics

Table 1. Absolute ratings (limiting values, with terminals 1 and 3 short circuited, at 25 °C, unless otherwise specified)

Symbol	Parameter	Value	Unit	
V _{RRM}	Repetitive peak reverse voltage	100	V	
I _{F(RMS)}	Forward rms current		30	А
I _{F(AV)}	Average forward current δ = 0.5, square wave T_C = 125 °C		20	А
I _{FSM}	Surge non repetitive forward current t_p = 10 ms sinusoidal		350	А
P _{ARM}	Repetitive peak avalanche power	1080	W	
T _{stg}	Storage temperature range		-65 to +150	°C
Tj	Maximum operating junction temperature (1)	150	°C	

1. $(dP_{tot'}/dT_j) < (1/R_{th(j-a)})$ condition to avoid thermal runaway for a diode on its own heatsink.

Table 2. Thermal resistance parameter

Symbol	Parameter	Max. value	Unit
R _{th(j-c)}	Junction to case	1.3	°C/W

For more information, please refer to the following application note:

AN5088: Rectifiers thermal management, handling and mounting recommendations

Table 3. Static electrical characteristics (with terminals 1 and 3 short circuited)

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
		T _j = 25 °C		-	10	30	μA
I _R ⁽¹⁾	Deverse leekage eurrent	T _j = 125 °C	V _R = V _{RRM}	-	10	30	mA
IR W	Reverse leakage current	T _j = 25 °C	V _R = 70 V	-	5		μA
		T _j = 125 °C	v _R = 70 v	-	5		mA
		T _j = 25 °C	I _F = 5 A	-	565		
	Forward voltage drop	T _j = 125 °C		-	480		
V _F ⁽²⁾		T _j = 25 °C	I _F = 10 A	-	685		
VF (=)		T _j = 125 °C	IF - IOA	-	560	620	mV
		T _j = 25 °C	I _F = 20 A	-	800	900	
		T _j = 125 °C	1F - 20 A	-	630	700	

1. Pulse test: $t_p = 5 ms, \delta < 2\%$

2. Pulse test: $t_p = 380 \ \mu s, \ \delta < 2\%$

To evaluate the conduction losses, use the following equation:

 $P = 0.6 \times I_{F(AV)} + 0.005 \times I_{F}^{2} (RMS)$

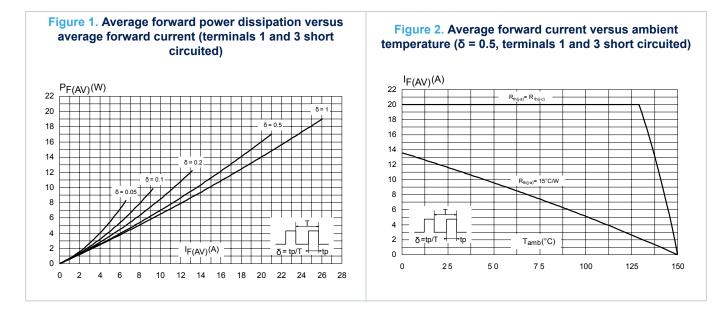
For more information, please refer to the following application notes related to the power losses:

AN604: Calculation of conduction losses in a power rectifier

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AN4021: Calculation of reverse losses on a power diode

1.1 Characteristics (curves)



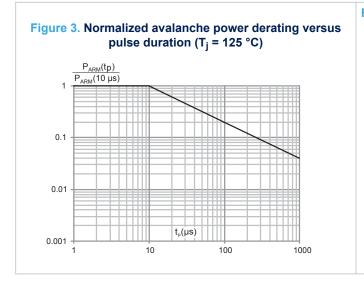
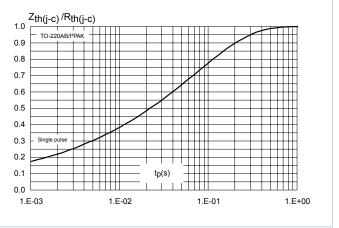


Figure 4. Relative variation of thermal impedance junction to case versus pulse duration





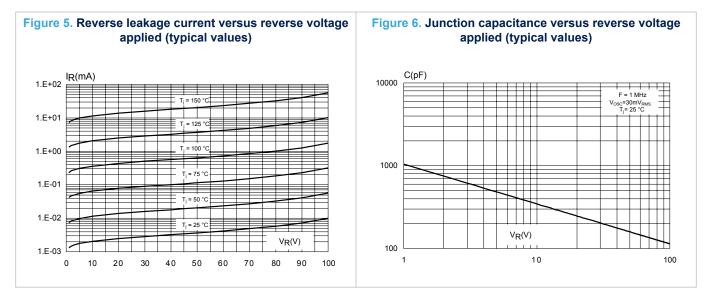
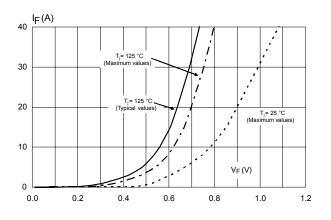


Figure 7. Forward voltage drop versus forward current (terminals 1 and 3 short circuited)



2 Package information

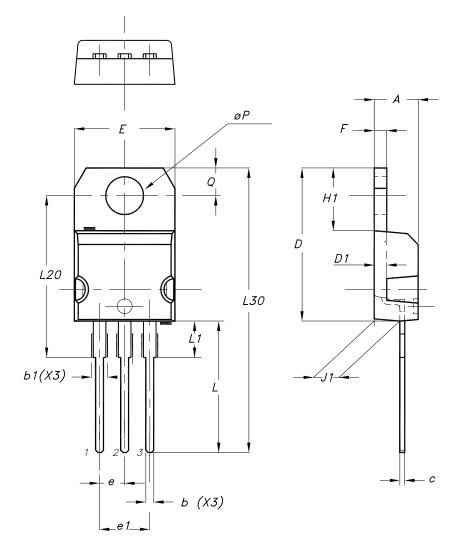
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In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

2.1 TO-220AB package information

- Epoxy meets UL 94,V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.55 N·m
- Maximum torque value: 0.70 N·m

Figure 8. TO-220AB package outline



	Dimensions				
Ref.	Millin	Millimeters		ference only)	
	Min.	Max.	Min.	Max.	
А	4.40	4.60	0.173	0.181	
b	0.61	0.88	0.240	0.035	
b1	1.14	1.55	0.045	0.061	
С	0.48	0.70	0.019	0.028	
D	15.25	15.75	0.600	0.620	
D1	1.27	typ.	0.050 typ.		
E	10.00	10.40	0.394	0.409	
е	2.40	2.70	0.094	0.106	
e1	4.95	5.15	0.195	0.203	
F	1.23	1.32	0.048	0.052	
H1	6.20	6.60	0.244	0.260	
J1	2.40	2.72	0.094	0.107	
L	13.00	14.00	0.512	0.551	
L1	3.50	3.93	0.138	0.155	
L20	16.40	16.40 typ.		δ typ.	
L30	28.90	28.90 typ.		З typ.	
θΡ	3.75	3.85	0.148	0.152	
Q	2.65	2.95	0.104	0.116	

Table 4. TO-220AB package mechanical data

2.2 I²PAK package information

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- Cooling method: by conduction (C)
- Epoxy meets UL 94,V0

Figure 9. I²PAK package outline

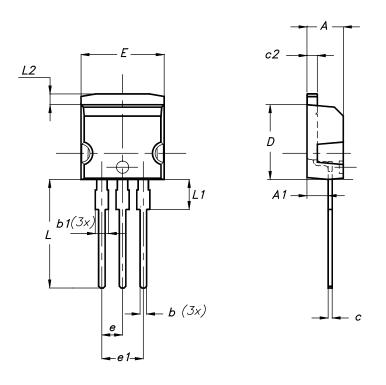


Table 5. I²PAK package mechanical data

	Dimensions				
Ref.	Millim	Millimeters		erence only)	
	Min.	Max.	Min.	Max.	
А	4.40	4.60	0.173	0.181	
A1	2.40	2.72	0.094	0.107	
b	0.61	0.88	0.024	0.035	
b1	1.14	1.70	0.044	0.067	
С	0.49	0.70	0.019	0.028	
c2	1.23	1.32	0.048	0.052	
D	8.95	9.35	0.352	0.368	
е	2.40	2.70	0.094	0.106	
e1	4.95	5.15	0.195	0.203	
E	10.00	10.40	0.394	0.409	
L	13.00	14.00	0.512	0.551	
L1	3.50	3.93	0.138	0.155	
L2	1.27	1.40	0.050	0.055	



3 Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS20SM100ST	PS20SM100ST	TO-220AB	1.95 g	50	Tube
STPS20SM100SR	PS20SM100SR	I²PAK	1.50 g	50	Tube

Table 6. Ordering information

Revision history

Table 7. Document	revision	history
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Date	Revision	Changes
25-Mar-2009	1	First issue.
16-Apr-2010	2	Updated package graphic for TO-220AB on front page and in Table 5.
11-May-2017	3	Removed TO-220FPAB and D ² PAK packages.
17-Oct-2018	4	Updated cover page and Table 1. Absolute ratings (limiting values, with terminals 1 and 3 short circuited, at 25 °C, unless otherwise specified). Removed figure 1 and figure 9. Minor text changes to improve readability.



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